CC1310 RF

VDDS Decoupling Capacitors

Place L1 and C8 close to pin 33

VDDR Decoupling Capacitors

To use RF test connector, remove R12 and mount 0-ohm resistor R13

C24, R12 and C23 for antenna matching

CC1310 IO block placed on page 2.
XDS110 Debugger Interface

P10 selects the voltage source for the level shifters
When powering CC1310 from the XDS supply, connect jumper between pins 1 and 2.
When powering CC1310 from the external supply, connect jumper between pins 2 and 3

M12 jumper to be mounted between pin 1 and 2 on header P10

M1-M11 jumpers to be mounted on header P4

Use P5 for debugging CC1310 with an external debugger (requires that all jumpers on P4 be removed)
Use P7 for debugging external targets (requires that all jumpers on P4 be removed)
XDS110 Debugger

XDS_VCC = 3.3 V

Title: TIDA-010003

Drawn: TER, KHT
Checked: KHT

Standard: LAUNCHXL-CC1310

Date: Thursday, January 21, 2016

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